ABSTRACT

The invention generally relates to a method of, and an apparatus for, inspecting low pin integrated circuit package three-dimensional features, especially the lead geometry. In particular, the invention is used in conjunction with a high speed rotary indexed machine that uses pick-up heads to transport and process the integrated circuit. The invention acquires two substantially orthogonal views of the integrated circuit consisting of end and bottom views. Image processing means are applied to measure the three dimensional features of the integrated circuit leads and package. The invention does not come into contact with, nor cause obstruction to the motion of, the integrated circuit.

This Sheet Has Been Replaced